

# HAL115 Hall Effect Sensor IC

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6251-414-1DS



## Hall Effect Sensor IC in CMOS technology

### Features:

- operates from 4.3 to 24 V supply voltage with reverse voltage protection
- operates with magnetic fields from DC to 20 kHz
- overvoltage and reverse-voltage protection
- on-chip temperature compensation circuitry minimizes shifts in on and off points and hysteresis over temperature and supply voltage
- the decrease of magnetic flux density caused by rising temperature in the sensor system is compensated by a built-in negative temperature coefficient of hysteresis
- ideal sensor for speed measurement, revolution counting, positioning, and DC brushless motors
- short-circuit protection

### Specifications

- switching type: bipolar
- output turns low with magnetic south pole on branded side of package
- output can change, if magnetic pole is removed

### Marking Code

Type	Temperature Range	
	E	C
HAL 115UA	115E	115C
HAL 115S	115E	115C

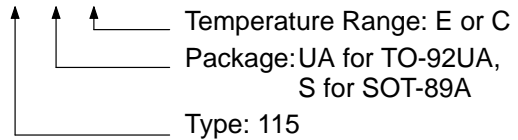
### Operating Junction Temperature Range

**E:**  $T_J = -40\text{ °C to }+100\text{ °C}$

**C:**  $T_J = 0\text{ °C to }+100\text{ °C}$

### Designation of Hall Sensors

HALXXXPP-T

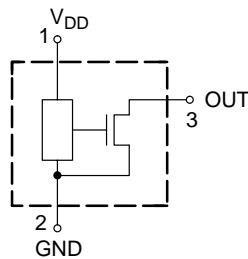


Example: **HAL 115UA-E**

- Type: 115
- Package: TO-92UA
- Temperature Range:  $T_J = -40\text{ °C to }+100\text{ °C}$

### Solderability

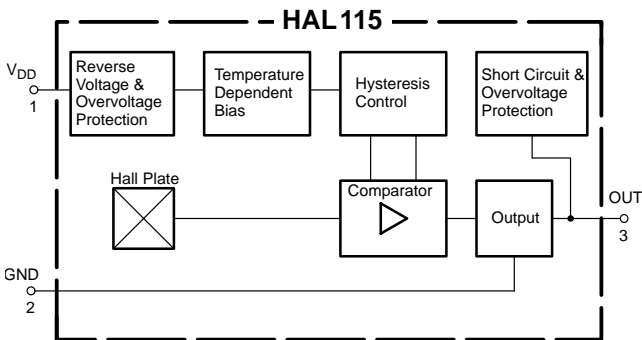
- Package SOT-89A: according to IEC68-2-58
- Package TO-92UA: according to IEC68-2-20



**Fig. 1:** Pin configuration

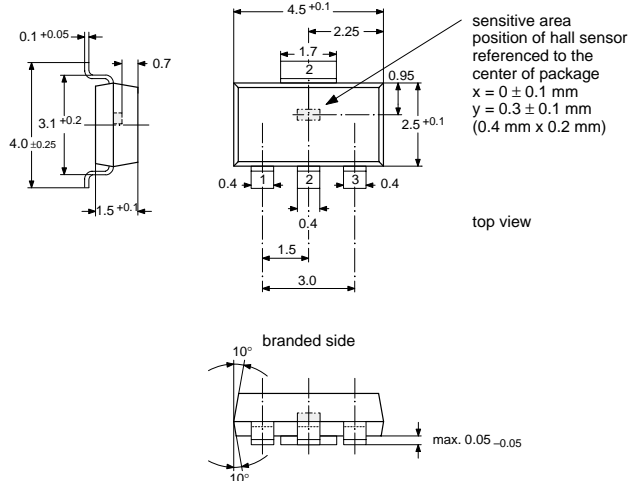
**Functional Description**

This Hall effect sensor is a monolithic integrated circuit that switches in response to magnetic fields. If a magnetic field with flux lines at right angles to the sensitive area is applied to the sensor, the biased Hall plate forces a Hall voltage proportional to this field. The Hall voltage is compared with the actual threshold level in the comparator. The temperature-dependent bias increases the supply voltage of the Hall plates and adjusts the switching points to the decreasing induction of magnets at higher temperatures. If the magnetic field exceeds the threshold levels, the open drain output switches to the appropriate state. The built-in hysteresis eliminates oscillation and provides switching behavior of output without bounce. The output is short-circuit protected by limiting high currents and by sensing excess temperature. Shunt protection devices clamp voltage peaks at the Output-Pin and  $V_{DD}$ -Pin together with external series resistors. Reverse current is limited at the  $V_{DD}$ -Pin by an internal series resistor up to  $-15\text{ V}$ . No external reverse protection diode is needed at the  $V_{DD}$ -Pin for values ranging from  $0\text{ V}$  to  $-15\text{ V}$ .

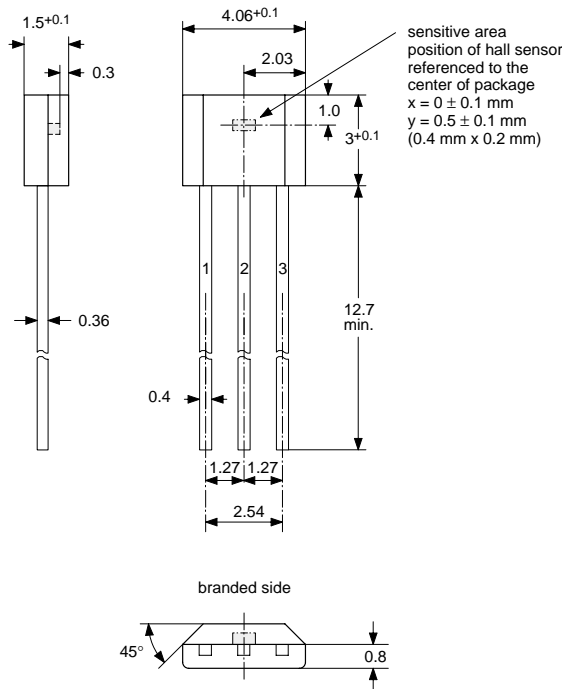


**Fig. 2:** HAL 115 block diagram

**Outline Dimensions**



**Fig. 3:**  
Plastic Small Outline Transistor Package (SOT-89A)  
Weight approximately 0.04 g  
Dimensions in mm



**Fig. 4:**  
Plastic Transistor Single Outline Package (TO-92UA)  
Weight approximately 0.12 g  
Dimensions in mm

## Absolute Maximum Ratings

Symbol	Parameter	Pin No.	Min.	Max.	Unit
$V_{DD}$	Supply Voltage	1	-15	28 <sup>1)</sup>	V
$V_{OH}$	Output Off Voltage	3	-	28 <sup>1)</sup>	V
$I_O$	Continuous Output On Current	3	-	20	mA
$I_O$	Peak Output On Current	3	-	250 <sup>2)</sup>	mA
$-I_{DD}$	Reverse Supply Current	1		25 <sup>1)</sup>	mA
$T_s$	Storage Temperature Range		-65	150	°C
$T_J$	Junction Temperature Range		-40	150	°C
<sup>1)</sup> as long as $T_{Jmax}$ is not exceeded <sup>2)</sup> $t < 2$ ms					

Stresses beyond those listed in the “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at these or any other conditions beyond those indicated in the “Recommended Operating Conditions/Characteristics” of this specification is not implied. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

## Recommended Operating Conditions

Symbol	Parameter	Pin No.	Min.	Typ.	Max.	Unit
$V_{DD}$	Supply Voltage	1	4.3	-	24	V
$I_O$	Continuous Output On Current	3	0	-	12.5	mA
$R_S$	Series Resistor	1	-	-	270	$\Omega$

**Electrical Characteristics** at  $T_J = -40$  °C to  $+100$  °C,  $V_{DD} = 4.3$  V to 24 V,  
 Typical Characteristics for  $T_J = 25$  °C and  $V_{DD} = 12$  V

Symbol	Parameter	Pin No.	Min.	Typ.	Max.	Unit	Test Conditions
$V_{OL}$	Output Voltage	3	-	125	250	mV	$I_O = 12.5$ mA, $T_J = 25$ °C
$V_{OL}$	Output Voltage over Temperature Range	3	-	125	400	mV	$I_O = 12.5$ mA
$I_{OH}$	Output Leakage Current	3	-	-	1	$\mu$ A	$B < B_{OFF}$ , $T_J = 25$ °C $V_{DD} \leq 20$ V
$I_{OH}$	Output Leakage Current over Temperature Range	3	-	-	10	$\mu$ A	$B < B_{OFF}$
$I_{DD}$	Supply Current	1	6.5	8.3	11	mA	$T_J = 25$ °C, $V_{DD} = 12$ V
$I_{DD}$	Supply Current over Temperature Range	1	5.5	8.3	12	mA	

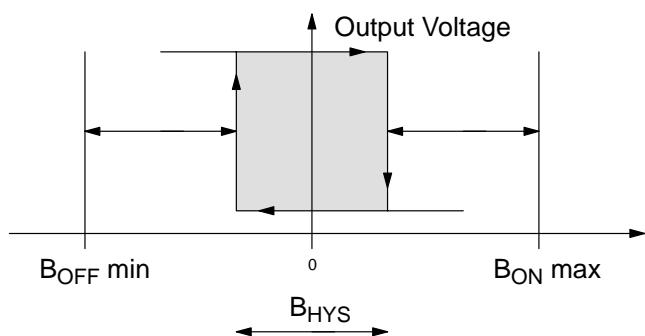
**Electrical Characteristics, continued**

Symbol	Parameter	Pin No.	Min.	Typ.	Max.	Unit	Test Conditions
$t_{en(O)}$	Enable Time of Output after Setting of $V_{DD}$	3	–	6	50	$\mu\text{s}$	$V_{DD} = 12\text{ V}$
$t_r$	Output Rise Time	3	–	85	400	ns	$V_{DD} = 12\text{ V}$ , $R_L = 820\text{ Ohm}$ , $C_L = 20\text{ pF}$
$t_f$	Output Fall Time	3	–	60	400	ns	$V_{DD} = 12\text{ V}$ , $R_L = 820\text{ Ohm}$ , $C_L = 20\text{ pF}$
$R_{thJSB}$ case SOT-89A	Thermal Resistance Junction to Substrate Backside		–	150	200	K/W	Fiberglass Substrate, 30 mm x 10 mm x 1,5mm pad size see Fig. 6
$R_{thJA}$ case TO-92UA	Thermal Resistance Junction to Soldering Point		–	150	200	K/W	Leads at ambient temperature at a distance of 2 mm from case

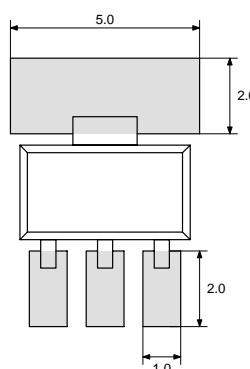
**Magnetic Characteristics** at  $T_J = -40\text{ }^\circ\text{C}$  to  $+100\text{ }^\circ\text{C}$ ,  $V_{DD} = 4.3\text{ V}$  to  $24\text{ V}$ ,  
 Typical Characteristics for  $T_J = 25\text{ }^\circ\text{C}$  and  $V_{DD} = 12\text{ V}$

Magnetic flux density values of switching points.  
 Positive flux density values refer to the magnetic south pole at the branded side of the package.

Parameter	Min.	Typ.	Max.	Unit
On point $B_{ON}$	-10.7	1.2	12.5	mT
Off point $B_{OFF}$	-12.5	-1.2	10.7	mT
Hysteresis $B_{HYS}$	1.8	2.4	7	mT



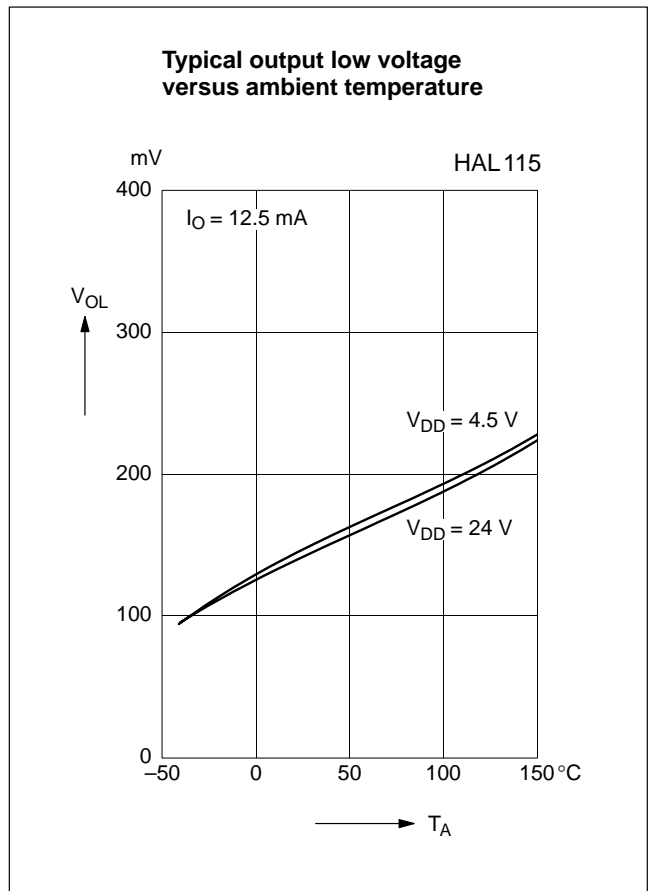
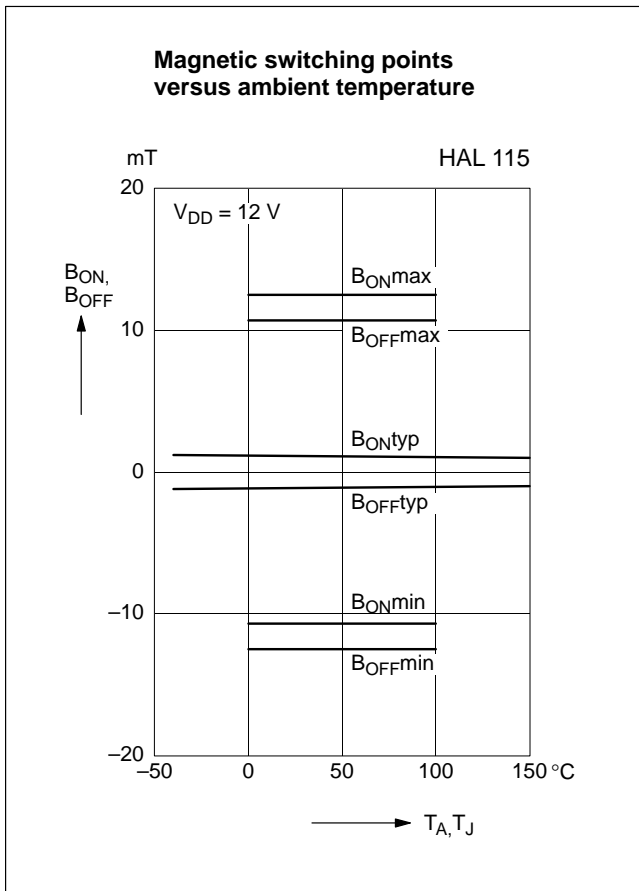
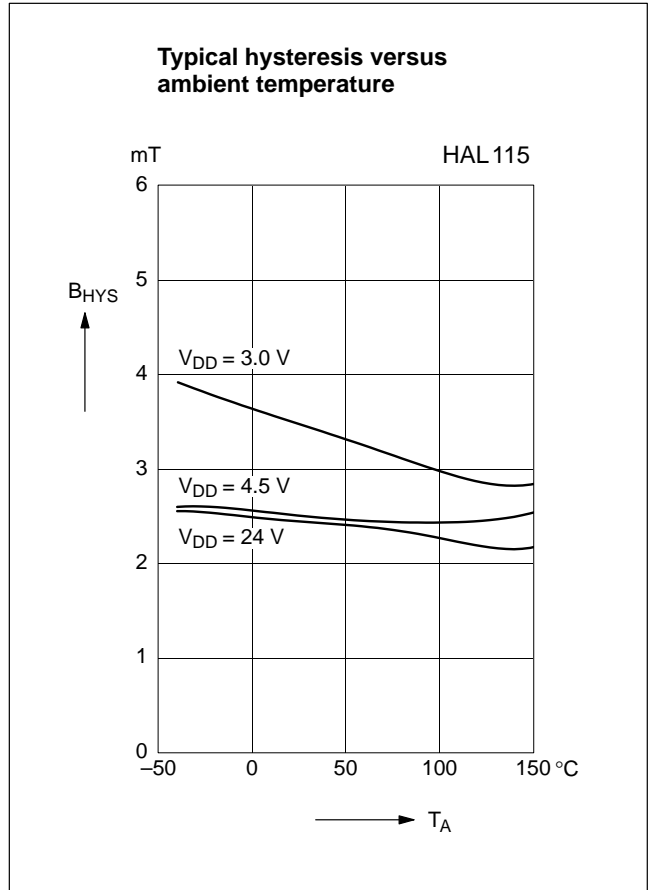
**Fig. 5:** Definition of magnetic switching points and hysteresis



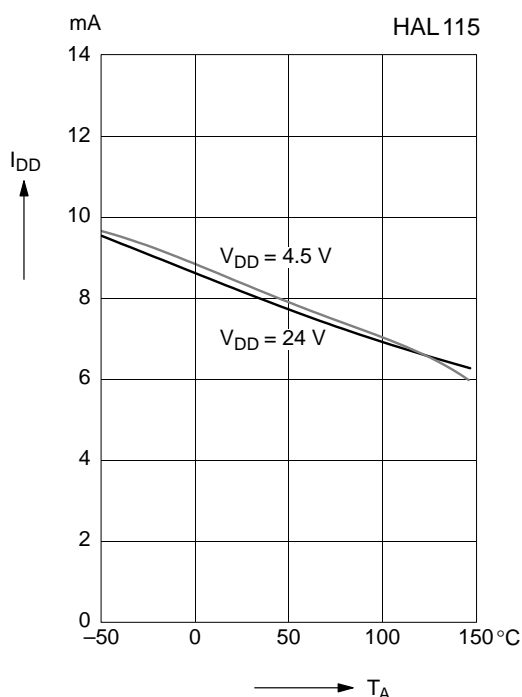
**Fig. 6:** Recommended pad size SOT-89A  
 Dimensions in mm

**Note 1:** In the following diagrams “Magnetic switch points versus ambient temperature”, the curves for  $B_{ONmin}$ ,  $B_{ONmax}$ ,  $B_{OFFmin}$ , and  $B_{OFFmax}$  refer to junction temperature, whereas typical curves refer to ambient temperature.

**Note 2:** The dropping characteristic of the supply current versus the supply voltage is caused by the internal power dissipation.



**Typical supply current versus ambient temperature**



## Application Note

Because of inherent reverse voltage protection, no diode is needed at pin 1 for reverse voltages ranging from 0 V to -15 V.

For electromagnetic immunity, it is recommended to apply a 330 pF minimum capacitor between  $V_{DD}$  (pin 1) and Ground (pin 2).

For applications requiring robustness to conducted disturbances (transients), a 220  $\Omega$  series resistor to pin 1 and a 4.7 nF capacitor between  $V_{DD}$  (pin 1) and Ground (pin 2) is recommended.

Because of the  $I_{DD}$  peak at 4.1 V, the series resistor should not be greater than 270  $\Omega$ .

The series resistor and the capacitor should be placed as close as possible to the IC.

## Ambient Temperature

Due to the internal power dissipation, the temperature on the silicon chip (junction temperature  $T_J$ ) is higher than the temperature outside the package (ambient temperature  $T_A$ ).

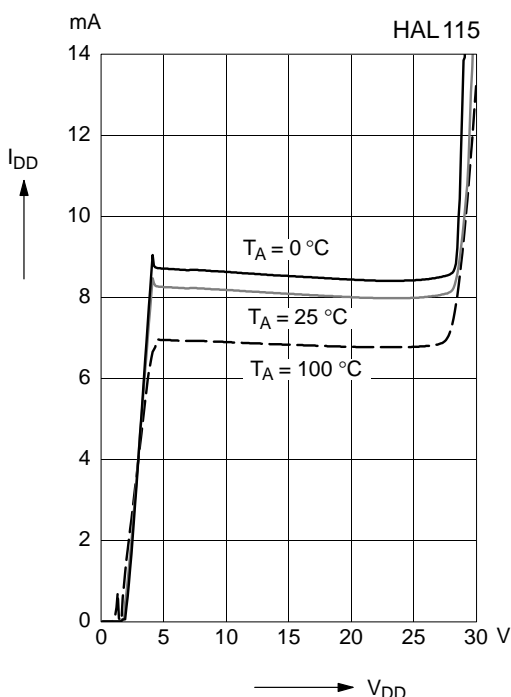
$$T_J = T_A + \Delta T$$

At static conditions, the following equations are valid:

- for SOT-89A:  $\Delta T = I_{DD} \cdot V_{DD} \cdot R_{thJSB}$
- for TO-92UA:  $\Delta T = I_{DD} \cdot V_{DD} \cdot R_{thJA}$

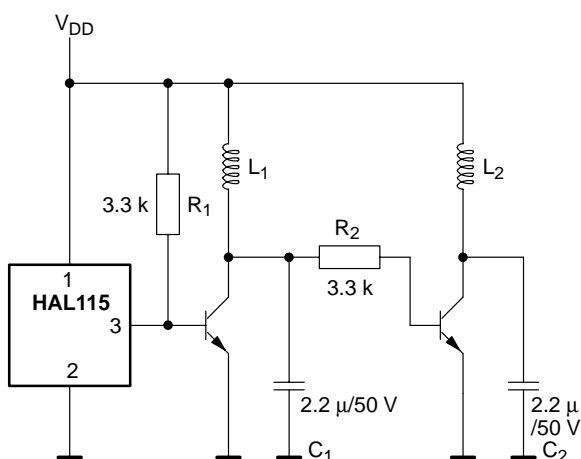
For typical values, use the typical parameters. For worst case calculation, use the max. parameters for  $I_{DD}$  and  $R_{th}$ , and the max. value for  $V_{DD}$  from the application.

**Typical supply current versus supply voltage**



see note 2

## Recommended Application Circuit for DC Fans



## Data Sheet History

1. Final data sheet: "HAL 115 Hall Effect Sensor IC", May 7, 1997, 6251-414-1DS. First release of the final data sheet.

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